

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/19/10690	
1.3 Title of PCN	ASE Kaohsiung (Taiwan) additional source for UFBGA 5X5 7x7 10x10 package products	
1.4 Product Category	UFBGA 5X5 7x7 10x10 listed products	
1.5 Issue date	2019-03-08	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	FRANK SCHIFANO
2.1.2 Phone	+1 5148333778
2.1.3 Email	frank.schifano@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ASE Kaohsiung Taiwan

4. Description of change

	Old	New
4.1 Description	Back-end source: - Amkor ATP Philippines	Back-end sources: - Amkor ATP Philippines - ASE Kaohsiung Taiwan - Additional source For more information, please refer to PCN10690 – Additional information attached document.
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	Visual aspect (color) might change depending on substrate material. Package darkness might change depending on molding compound. Ball1 identifier remain in the same corner but might change in terms of form and positioning. Marking position and size could be different upon assembly site, without any loss of information.	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Change is visible through assembly traceability plant, in the marking: - "7B" for Amkor ATP Philippines - "AA" for ASE Kaohsiung Taiwan Please refer to PCN 10690 – Additional information attached document.
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7. Timing / schedule

7.1 Date of qualification results	2019-04-24
7.2 Intended start of delivery	2019-05-24
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	10690 MDG-MCD-RER1901-PCN 10690-ASE Kaohsiung additional source for UFBGA 5x5_7x7_10x10.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2019-03-08

9. Attachments (additional documentations)

10690 Public product.pdf
10690 MDG-MCD-RER1901-PCN 10690-ASE Kaohsiung additional source for UFBGA 5x5_7x7_10x10.pdf
10690 PCN10690_Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F407IGH6	
	STM32H753IIK6	

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